

ABSTRACT

SEALING COMPOSITION AND SEMICONDUCTOR DEVICE

A first sealing composition includes an epoxy resin, a curing agent, an inorganic filler, and an unbaked hydrotalcite compound having a mole ratio of Mg ion to Al ion (Mg/Al) of 2.4 or more. A second sealing composition includes an epoxy resin, a curing agent, a hydrotalcite compound represented by Formula (1): $\text{Mg}_{1-x}\text{Al}_x(\text{OH})_2(\text{CO}_3)_{x/2} \cdot m\text{H}_2\text{O}$, in which each of x and m independently represents a positive number, and a magnesium-containing compound that is different from the hydrotalcite compound. A third sealing composition includes an epoxy resin, a curing agent, a hydrotalcite compound represented by Formula (I), and a magnesium oxide, and a content of the magnesium oxide is from 1 part by mass to 50 parts by mass parts with respect to 100 mass parts of the epoxy resin.